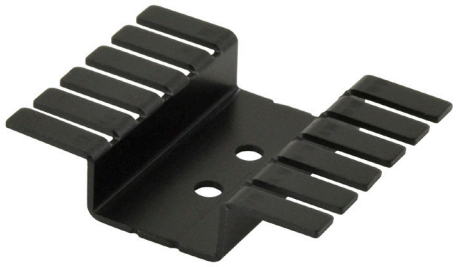
MODEL: HSS-B20-NP-04 | DESCRIPTION: HEAT SINK

FEATURES

- TO-220 package
- round hole for component attachment
- two hole options for longer component pins
- black anodized finish



RoHS

MODEL

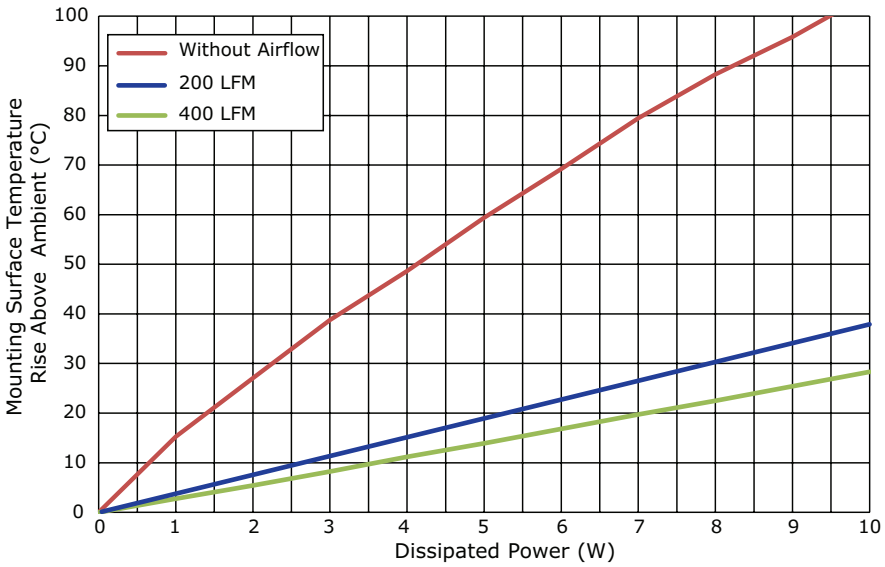
MODEL	thermal resistance[1] @ 75°C ΔT, nat conv (°C/W)	@ 1 W, nat conv (°C/W)	@ 1 W, 200 LFM (°C/W)	@ 1 W, 400 LFM (°C/W)	power dissipation[1] @ 75°C ΔT, nat conv (W)
HSS-B20-NP-04	11.54	15.27	3.76	2.74	6.50

Note: 1. See performance curves for full thermal resistance details.

PERFORMANCE CURVES

	Heatsink Temperature Rise Above Ambient (ΔT = Ths - Ta) (°C)		
Power (W)	Natural Conv.	200 LFM	400 LFM
0	0	0	0
1	15.27	3.76	2.74
2	27.05	7.51	5.43
3	38.74	11.26	8.23
4	48.62	15.04	11.17
5	59.41	18.81	13.89
6	69.24	22.56	16.83
7	79.43	26.28	19.71
8	88.27	30.18	22.48
9	95.85	33.95	25.41
10	104.56	37.87	28.29

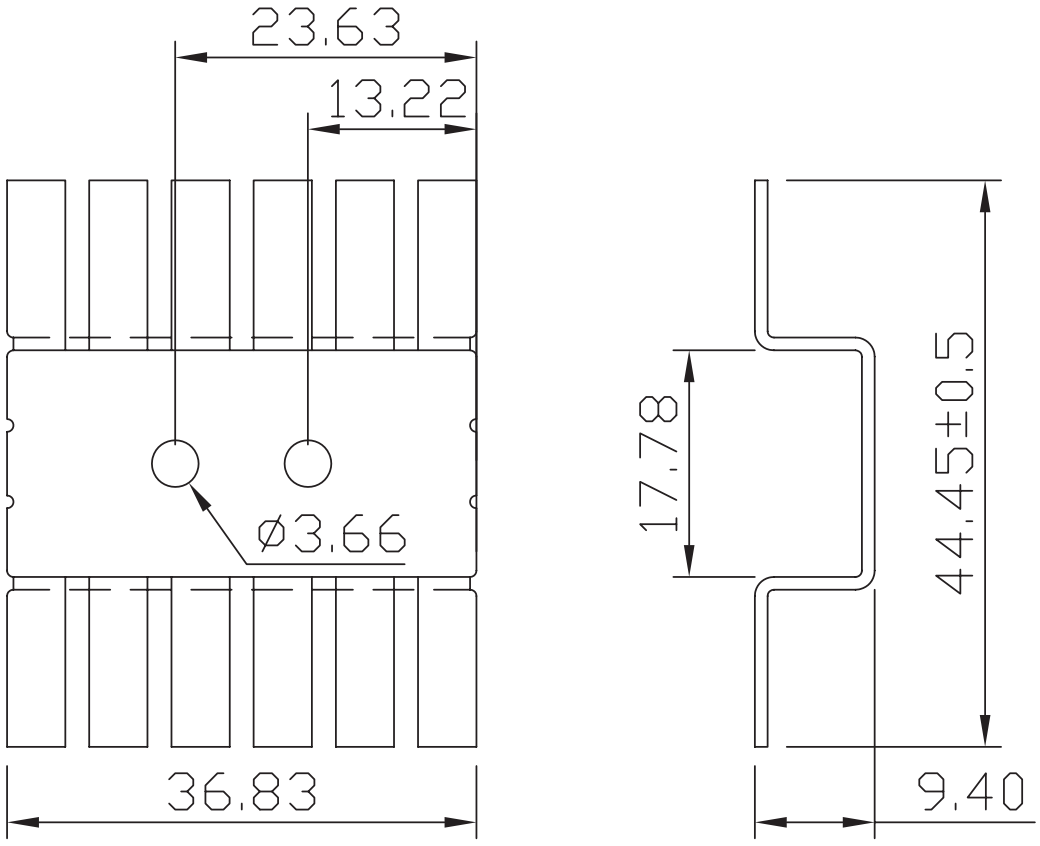
Ths: "hot spot" temperature measured on the heatsink
Ta: ambient temperature



MECHANICAL DRAWING

units: mm
tolerance: ±0.5 mm

MATERIAL	AL1050
FINISH	black anodized
THICKNESS	1.0 mm
WEIGHT	5.7 g



REVISION HISTORY

rev.	description	date
1.0	initial release	04/03/2017
1.01	brand update	02/13/2020
1.02	logo, datasheet style update	08/05/2022
1.03	CUI Devices rebranded to Same Sky	09/12/2024

The revision history provided is for informational purposes only and is believed to be accurate.